



## Material Content Data Sheet



<b>Sales Product Name</b>		BA 895 H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000770644						
<b>Package</b>		PG-SCD80-2-1		<b>Weight*</b>		1.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		33	
	noble metal	gold	7440-57-5	0.006	0.32		3230	
	inorganic material	silicon	7440-21-3	0.052	2.76	3.08	27585	30848
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		395	
	non noble metal	chromium	7440-47-3	0.002	0.12		1185	
	non noble metal	copper	7440-50-8	0.744	39.33	39.50	393310	394969
wire	non noble metal	copper	7440-50-8	0.002	0.12	0.12	1165	1165
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5085	
	plastics	epoxy resin	-	0.164	8.64		86448	
	inorganic material	silicondioxide	60676-86-0	0.789	41.70	50.85	416982	508515
leadfinish	non noble metal	tin	7440-31-5	0.036	1.90	1.90	19027	19027
plating	noble metal	silver	7440-22-4	0.086	4.55	4.55	45476	45476
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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